

Pch -100V -13A Power MOSFET

Datasheet

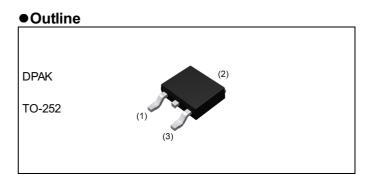
V _{DSS}	-100V
R _{DS(on)} (Max.)	200mΩ
I _D	±13A
P _D	20W

Features

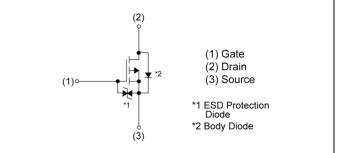
Application

Switching

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating ; RoHS compliant



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
_	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2500
	Toping and	TL
	Taping code	TL1
	Marking	RD3P130SP

• Absolute maximum ratings (T_a = 25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-100	V
Continuous drain current	۱ _D *1	±13	А
Pulsed drain current	ا _{DP} *2	±52	А
Gate - Source voltage	V _{GSS}	±20	V
Power dissipation	P _D ^{*3}	20	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

•Thermal resistance

Parameter	Symbol	Values			Linit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*3}	-	-	6.25	°C/W

• Electrical characteristics (T_a = 25°C)

Deverseter	Currente e l	Canditiana	Values			Linit
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	-91.3	-	mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -100V, V _{GS} = 0V	-	-	-1	μA
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±10	μA
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = -10V , I _D = -1mA	-1.0	I	-2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	3.0	-	mV/°C
		V _{GS} = -10V, I _D = -6.5A	-	135	200	
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = -4.5V, I _D = -6.5A	-	150	220	mΩ
		V _{GS} = -4.0V, I _D = -6.5A	-	155	230	
Gate resistance	R _G	f = 1MHz, open drain	-	6.0	-	Ω
Forward Transfer Admittance	Y _{fs} ^{*4}	V _{DS} = -10V, I _D = -13A	10	-	-	S

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 T_C=25°C

*4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumphal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	2400	-	
Output capacitance	C _{oss}	V _{DS} = -25V	-	100	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	65	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -50V, V_{GS} = -10V$	-	20	-	
Rise time	t _r *4	I _D = -6.5A	-	25	-	20
Turn - off delay time	t _{d(off)} *4	R _L ≃ 7.68Ω	-	70	-	ns
Fall time	t _f *4	R _G = 10Ω	-	60	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Parameter	Symbol Conditions		Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*4}	עם ≃ -5 0V,	-	40	-	
Gate - Source charge	Q _{gs} *4	V _{DD} ≃ -50V, I _D = -13A, V _{GS} = -10V	-	6	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V _{GS} = -10V	-	6	-	

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _s *1	T - 25°0	-	-	-13	А
Pulse forward current	I _{SP} *2	T _a = 25°C	-	-	-52	А
Forward voltage	V_{SD}^{*4}	V _{GS} = 0V, I _S = -13A	-	-	-1.2	V



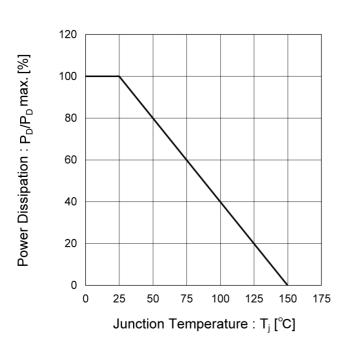


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

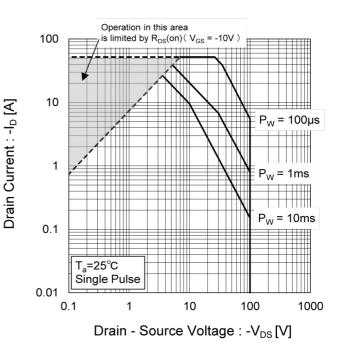
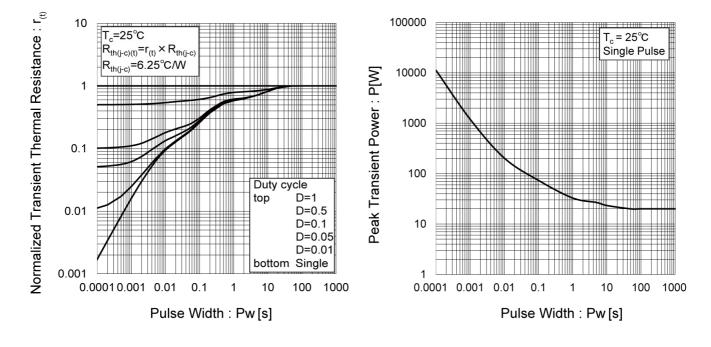


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation





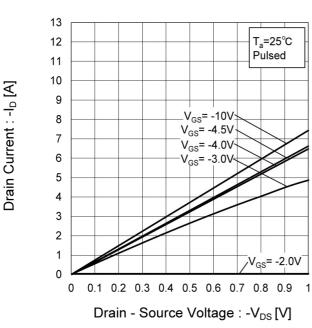


Fig.5 Typical Output Characteristics(I)

T_a=25°C

/V_{GS}= -2.0V

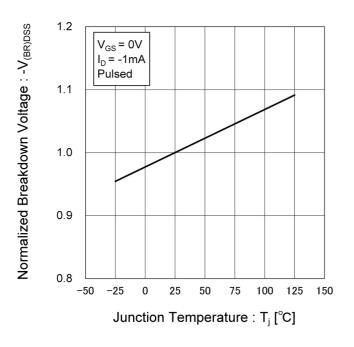
Drain Current : -I_D [A]

Pulsed

13 V_{GS}= -10V T_a=25°C 12 V_{GS}= -4.5V Pulsed 11 V_{GS}= -4.0V 10 9 V_{GS}= -3.0V 8 7 6 5 4 3 2 1 _V_{GS}= -2.0V 0 0 1 2 3 4 5 6 7 8 9 10 Drain - Source Voltage : -V_{DS} [V]

Fig.6 Typical Output Characteristics(II)

Fig.7 Breakdown Voltage vs. **Junction Temperature**





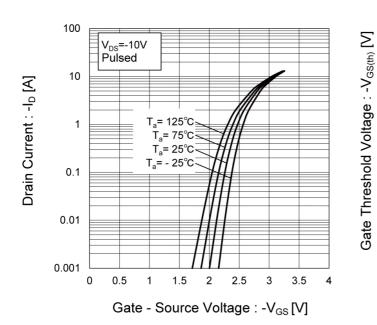


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

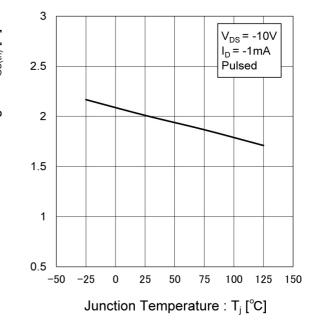
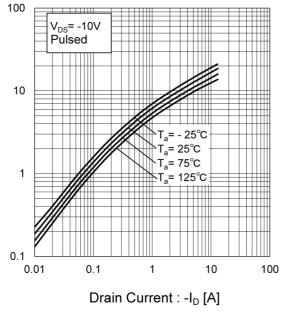


Fig.10 Forward Transfer Admittance vs. Drain Current

Forward Transfer Admittance : Y_{fs} [S]





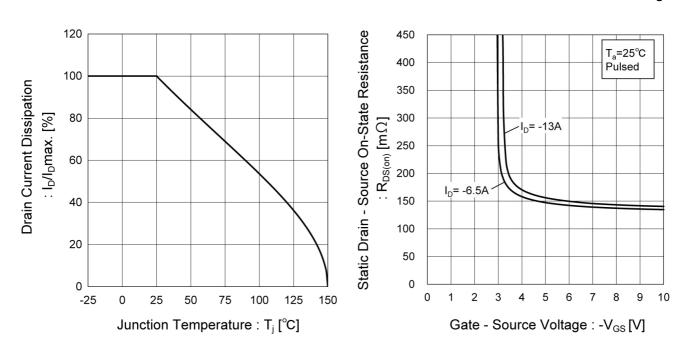
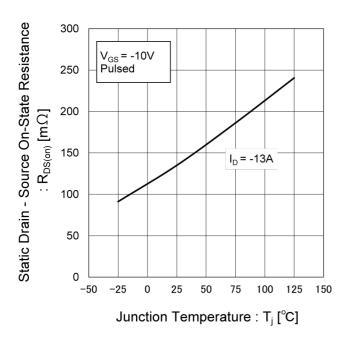


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







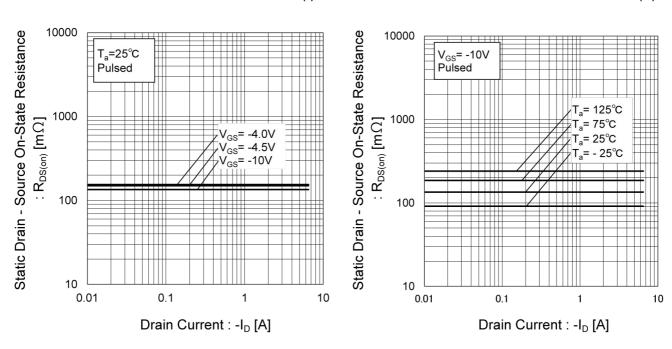


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

Fig.16 Static Drain - Source On - State

Resistance vs. Drain Current(III)

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

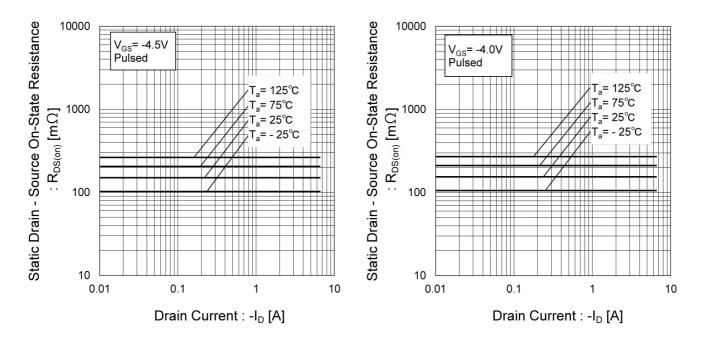


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)



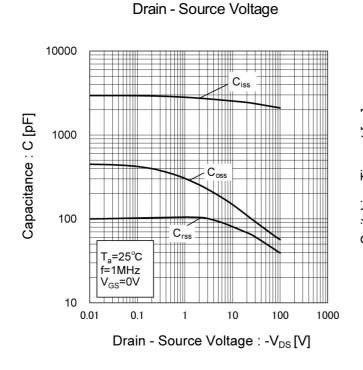


Fig.18 Typical Capacitance vs.

Fig.19 Switching Characteristics

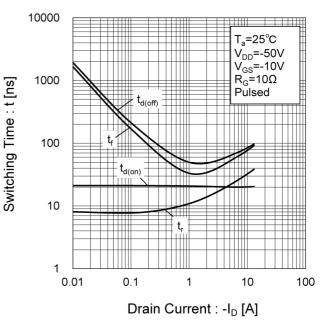


Fig.20 Dynamic Input Characteristics

Gate - Source Voltage : -V_{GS} [V]

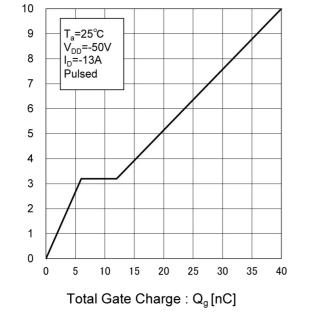
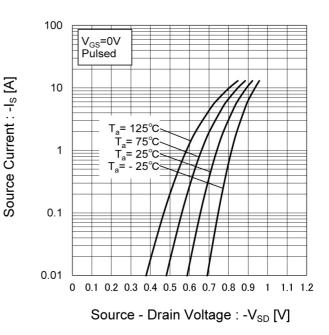


Fig.21 Source Current vs. Source Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

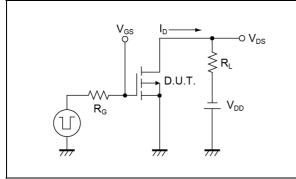


Fig.2-1 Gate Charge Measurement Circuit

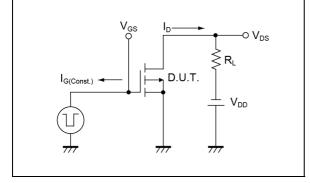
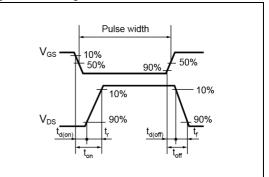
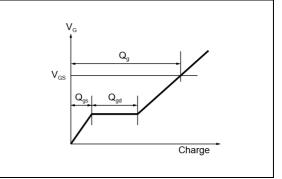


Fig.1-2 Switching Waveforms

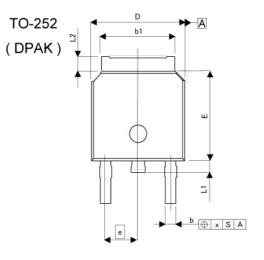


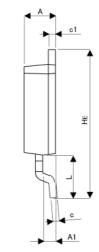


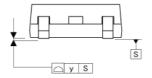


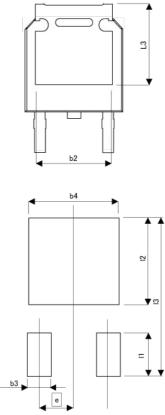


$\bullet \textit{Dimensions}(\mathsf{TL})$









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

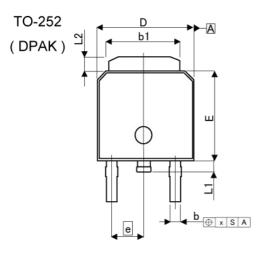
DIM	MILIMETERS INCHES		HES	
DIV	MIN	MAX	MIN	MAX
А	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	01
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.30		0.091	
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	2.90		14
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
х	-	0.10	-	0.004
у	-	0.10	-	0.004
DIM	MILIME	TERS	INC	HES

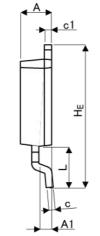
DIM	MILIMETERS		INC	NCHES	
Divi	MIN	MAX	MIN	MAX	
b3	-	1.10	2	0.043	
b4	-	5.40	-	0.213	
1	-	2.90	_	0.114	
12	-	5.50	-	0.217	
13	-	10.50	2	0.413	

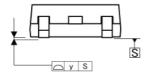
Dimension in mm/inches

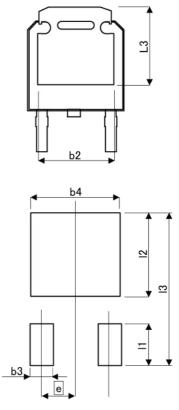


• Dimensions (TL1)









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
A	2.20	2.40	0.087	0.094	
A1	0.70	1.10	0.028	0.043	
b	0.60	0.90	0.024	0.035	
b1	5.20	5.50	0.205	0.217	
b2	4.	80	0.1	189	
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.40	6.80	0.252	0.268	
е	2.	30	0.0	091	
E	6.00	6.40	0.236	0.252	
HE	9.40	10.40	0.370	0.409	
L	2.	90	0.1	114	
L1	0.60	1.00	0.024	0.039	
L2	0.70	1.30	0.028	0.051	
L3	5.	30	0.209		
x	-	0.25	-	0.010	
у	-	0.10	-	0.004	
DIM	MILIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
b3	-	1.15	1-1	0.045	
b4	-	5.55		0.219	
1	-	2.77	-	0.109	
12	-	5.50	-	0.217	
13	-	10.40	-	0.409	

Dimension in mm/inches



Notice

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ		CLASSⅢ	

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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RD3P130SP - Web Page

Distribution Inventory

Part Number	RD3P130SP
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes